

# MC1458, MC1558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

SLOS069C – FEBRUARY 1971 – REVISED AUGUST 2010

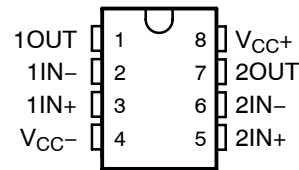
- Short-Circuit Protection
- Wide Common-Mode and Differential Voltage Ranges
- No Frequency Compensation Required
- Low Power Consumption
- No Latch-Up
- Designed to Be Interchangeable With Motorola MC1558/MC1458 and Signetics S5558/N5558

## description/ordering information

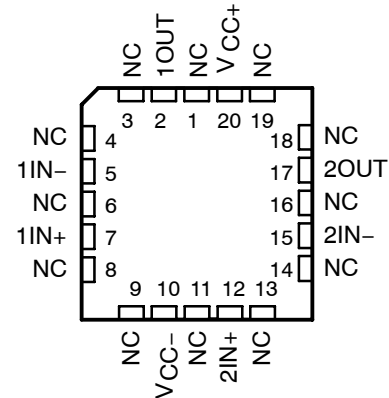
The MC1458 and MC1558 are dual general-purpose operational amplifiers, with each half electrically similar to the  $\mu$ A741, except that offset null capability is not provided.

The high-common-mode input voltage range and the absence of latch-up make these amplifiers ideal for voltage-follower applications. The devices are short-circuit protected and the internal frequency compensation ensures stability without external components.

MC1458 . . . D, P, OR PS PACKAGE  
MC1558 . . . JG PACKAGE  
(TOP VIEW)



MC1558 . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

## ORDERING INFORMATION

$T_A$	$V_{IOmax}$ AT 25°C	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	6 mV	PDIP (P)	Tube	MC1458P	MC1458P
		SOIC (D)	Tube	MC1458D	MC1458
			Tape and reel	MC1458DR	
		SOP (PS)	Tape and reel	MC1458PSR	M1458
-55°C to 125°C	5 mV	CDIP (JG)	Tube	MC1558JG	MC1558JG
		CDIP (JGB)	Tube	MC1558JGB	MC1558JGB
		LCCC (FK)	Tube	MC1558FK	MC1558FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265  
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251-1443

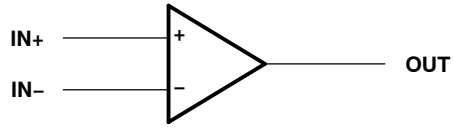
Copyright © 2002, Texas Instruments Incorporated  
On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# MC1458, MC1558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

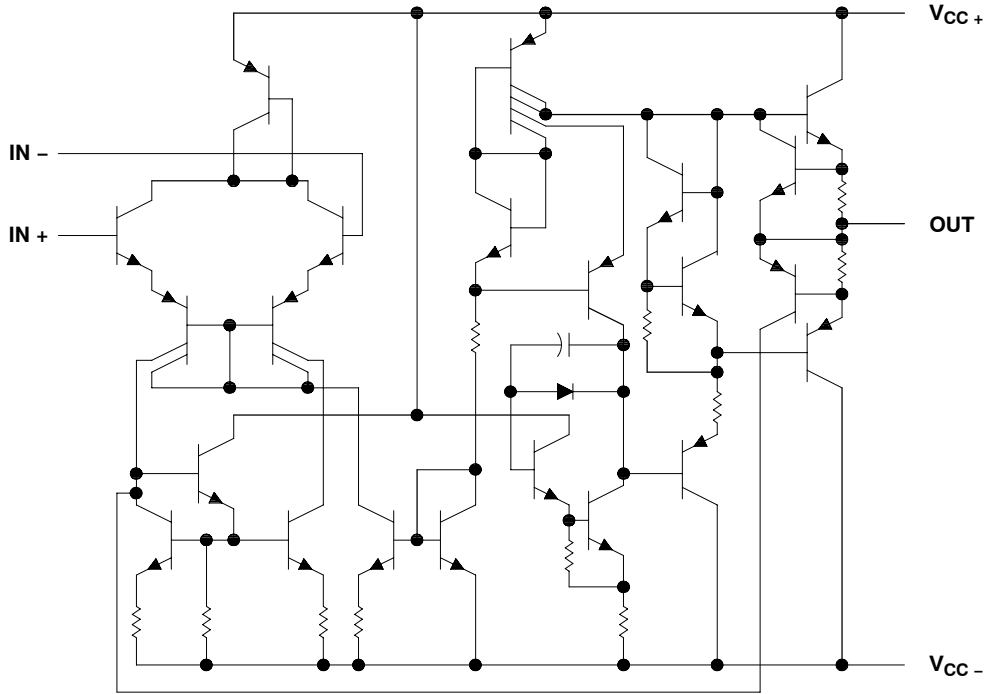
SLOS069C - FEBRUARY 1971 - REVISED AUGUST 2010

---

## symbol (each amplifier)



## schematic (each amplifier)



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265  
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251-1443

# MC1458, MC1558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

SLOS069C – FEBRUARY 1971 – REVISED AUGUST 2010

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, $V_{CC+}$ (see Note 1):	MC1458 .....	18 V
	MC1558 .....	22 V
Supply voltage, $V_{CC-}$ (see Note 1):	MC1458 .....	-18 V
	MC1558 .....	-22 V
Differential input voltage, $V_{ID}$ (see Note 2)	.....	±30 V
Input voltage, $V_I$ (either input, see Notes 1 and 3)	.....	±15 V
Duration of output short circuit (see Note 4)	.....	Unlimited
Operating virtual junction temperature, $T_J$	.....	150°C
Package thermal impedance, $\theta_{JA}$ (see Notes 5 and 6):	D package .....	97°C/W
	P package .....	85°C/W
	PS package .....	95°C/W
Package thermal impedance, $\theta_{JC}$ (see Notes 7 and 8):	FK package .....	5.61°C/W
	JG package .....	14.5°C/W
Case temperature for 60 seconds: FK package	.....	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: JG package	.....	300°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: D, P, or PS package	.....	260°C
Storage temperature range, $T_{stg}$	.....	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltage values, unless otherwise noted, are with respect to the midpoint between  $V_{CC+}$  and  $V_{CC-}$ .
  2. Differential voltages are at  $IN+$  with respect to  $IN-$ .
  3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
  4. The output can be shorted to ground or either power supply. For the MC1558 only, the unlimited duration of the short circuit applies at (or below) 125°C case temperature or 70°C free-air temperature.
  5. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
  6. The package thermal impedance is calculated in accordance with JESD 51-7.
  7. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JC}$ , and  $T_C$ . The maximum allowable power dissipation at any allowable case temperature is  $P_D = (T_J(max) - T_C)/\theta_{JC}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
  8. The package thermal impedance is calculated in accordance with MIL-STD-883.

## recommended operating conditions

		MIN	MAX	UNIT
$V_{CC\pm}$	Supply voltage	±5	±15	V
$T_A$	Operating free-air temperature range	MC1458	0    70	°C
		MC1558	-55    125	



# MC1458, MC1558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

SLOS069C – FEBRUARY 1971 – REVISED AUGUST 2010

## electrical characteristics at specified free-air temperature, $V_{CC\pm} = \pm 15\text{ V}$

PARAMETER	TEST CONDITIONS†	MC1458			MC1558			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
$V_{IO}$ Input offset voltage	$V_O = 0$	25°C	1	6	1	5	mV	
		Full range	7.5			6		
$I_{IO}$ Input offset current	$V_O = 0$	25°C	20	200	20	200	nA	
		Full range	300			500		
$I_{IB}$ Input bias current	$V_O = 0$	25°C	80	500	80	500	nA	
		Full range	800			1500		
$V_{ICR}$ Common-mode input voltage range		25°C	±12	±13	±12	±13	V	
		Full range	±12			±12		
$V_{OM}$ Maximum peak output voltage swing	$R_L = 10\text{ k}\Omega$	25°C	±12	±14	±12	±14	V	
	$R_L \geq 10\text{ k}\Omega$	Full range	±12			±11		
	$R_L = 2\text{ k}\Omega$	25°C	±10	±13	±10	±13		
	$R_L \geq 2\text{ k}\Omega$	Full range	±10			±10		
$A_{VD}$ Large-signal differential voltage amplification	$R_L \geq 2\text{ k}\Omega, V_O = \pm 10\text{ V}$	25°C	20	200	50	200	V/mV	
		Full range	15			25		
$B_{OM}$ Maximum-output-swing bandwidth (closed loop)	$R_L = 2\text{ k}\Omega, A_{VD} = 1, THD \geq 5\%$	25°C	14		14		kHz	
$B_1$ Unity-gain bandwidth		25°C	1		1		MHz	
$\phi_m$ Phase margin	$A_{VD} = 1$	25°C	65		65		deg	
		Gain margin	11		11			
$r_i$ Input resistance		25°C	0.3	2	0.3*	2	MΩ	
$r_o$ Output resistance	$V_O = 0,$ See Note 9	25°C	75		75		Ω	
$C_i$ Input capacitance		25°C	1.4		1.4		pF	
$z_{ic}$ Common-mode input impedance	$f = 20\text{ Hz}$	25°C	200		200		MΩ	
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICR}\text{ min}, V_O = 0$	25°C	70	90	70	90	dB	
		Full range	70			70		
$k_{SVS}$ Supply-voltage sensitivity ( $\Delta V_{IO}/\Delta V_{CC}$ )	$V_{CC} = \pm 9\text{ V to } \pm 15\text{ V}, V_O = 0$	25°C	30	150	30	150	μV/V	
		Full range	150			150		
$V_n$ Equivalent input noise voltage (closed loop)	$A_{VD} = 100, f = 1\text{ kHz}, R_S = 0, BW = 1\text{ Hz}$	25°C	45		45		nV/√Hz	
$I_{OS}$ Short-circuit output current		25°C	±25	±40	±25	±40	mA	
$I_{CC}$ Supply current (both amplifiers)	$V_O = 0, \text{ No load}$	25°C	3.4	5.6	3.4	5	mA	
		Full range	6.6			6.6		
$P_D$ Total power dissipation (both amplifiers)	$V_O = 0, \text{ No load}$	25°C	100	170	100	150	mW	
		Full range	200			200		
$V_{O1}/V_{O2}$ Crosstalk attenuation		25°C	120		120		dB	

\*On products compliant to MIL-PRF-38535, this parameter is not production tested.

† All characteristics are specified under open-loop operating conditions with zero common-mode input voltage, unless otherwise specified. Full range for MC1458 is 0°C to 70°C and for MC1558 is -55°C to 125°C.

NOTE 9: This typical value applies only at frequencies above a few hundred hertz because of the effect of drift and thermal feedback.



# MC1458, MC1558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

SLOS069C – FEBRUARY 1971 – REVISED AUGUST 2010

operating characteristics,  $V_{CC\pm} = \pm 15\text{ V}$ ,  $C_L = 100\text{ pF}$ ,  $T_A = 25^\circ\text{C}$  (see Figure 1)

PARAMETER		TEST CONDITIONS		MC1458			MC1558			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
$t_r$	Rise time	$V_I = 20\text{ mV}$ ,	$R_L = 2\text{ k}\Omega$ ,	0.3			0.3			$\mu\text{s}$
	Overshoot factor	$V_I = 20\text{ mV}$ ,	$R_L = 2\text{ k}\Omega$	5			5			%
SR	Slew rate at unity gain	$V_I = 10\text{ V}$ ,	$R_L = 2\text{ k}\Omega$	0.5			0.5			$\text{V}/\mu\text{s}$

## PARAMETER MEASUREMENT INFORMATION



Figure 1. Rise-Time, Overshoot, and Slew-Rate Waveform and Test Circuit

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9760301Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9760301Q2A MC1558FKB	<a href="#">Samples</a>
5962-9760301QPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9760301QPA MC1558	<a href="#">Samples</a>
MC1458D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MC1458	<a href="#">Samples</a>
MC1458DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MC1458	<a href="#">Samples</a>
MC1458DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MC1458	<a href="#">Samples</a>
MC1458DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MC1458	<a href="#">Samples</a>
MC1458DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	MC1458	<a href="#">Samples</a>
MC1458P	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	MC1458P	<a href="#">Samples</a>
MC1458PE4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	MC1458P	<a href="#">Samples</a>
MC1458PSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	M1458	<a href="#">Samples</a>
MC1558FKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9760301Q2A MC1558FKB	<a href="#">Samples</a>
MC1558JG	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	MC1558JG	<a href="#">Samples</a>
MC1558JGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9760301QPA MC1558	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of  $\leq 1000$ ppm threshold. Antimony trioxide based flame retardants must also meet the  $\leq 1000$ ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MC1458DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
MC1458DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
MC1458PSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1



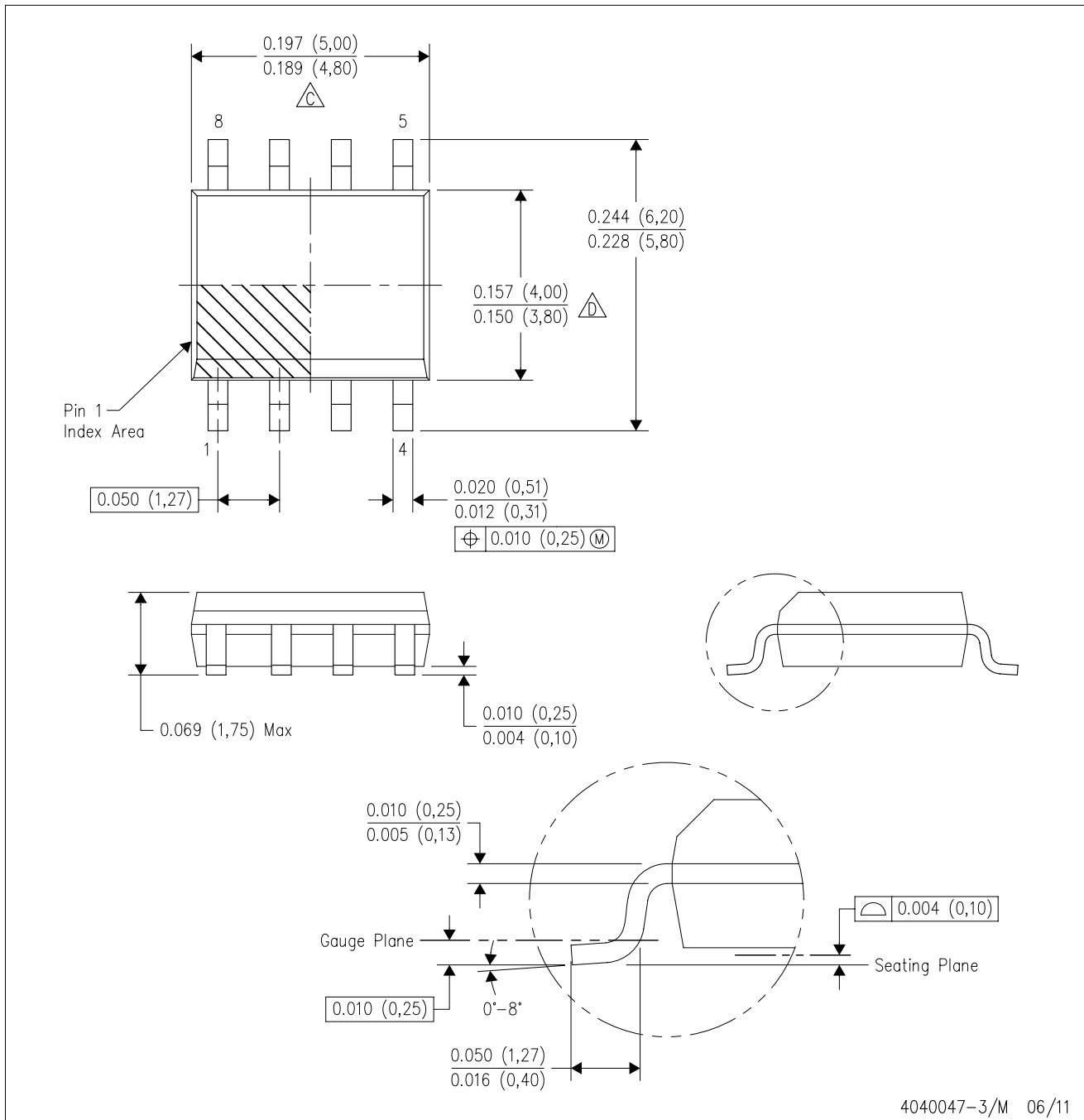
**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MC1458DR	SOIC	D	8	2500	367.0	367.0	35.0
MC1458DR	SOIC	D	8	2500	340.5	338.1	20.6
MC1458PSR	SO	PS	8	2000	367.0	367.0	38.0

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PS (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

JG (R-GDIP-T8)

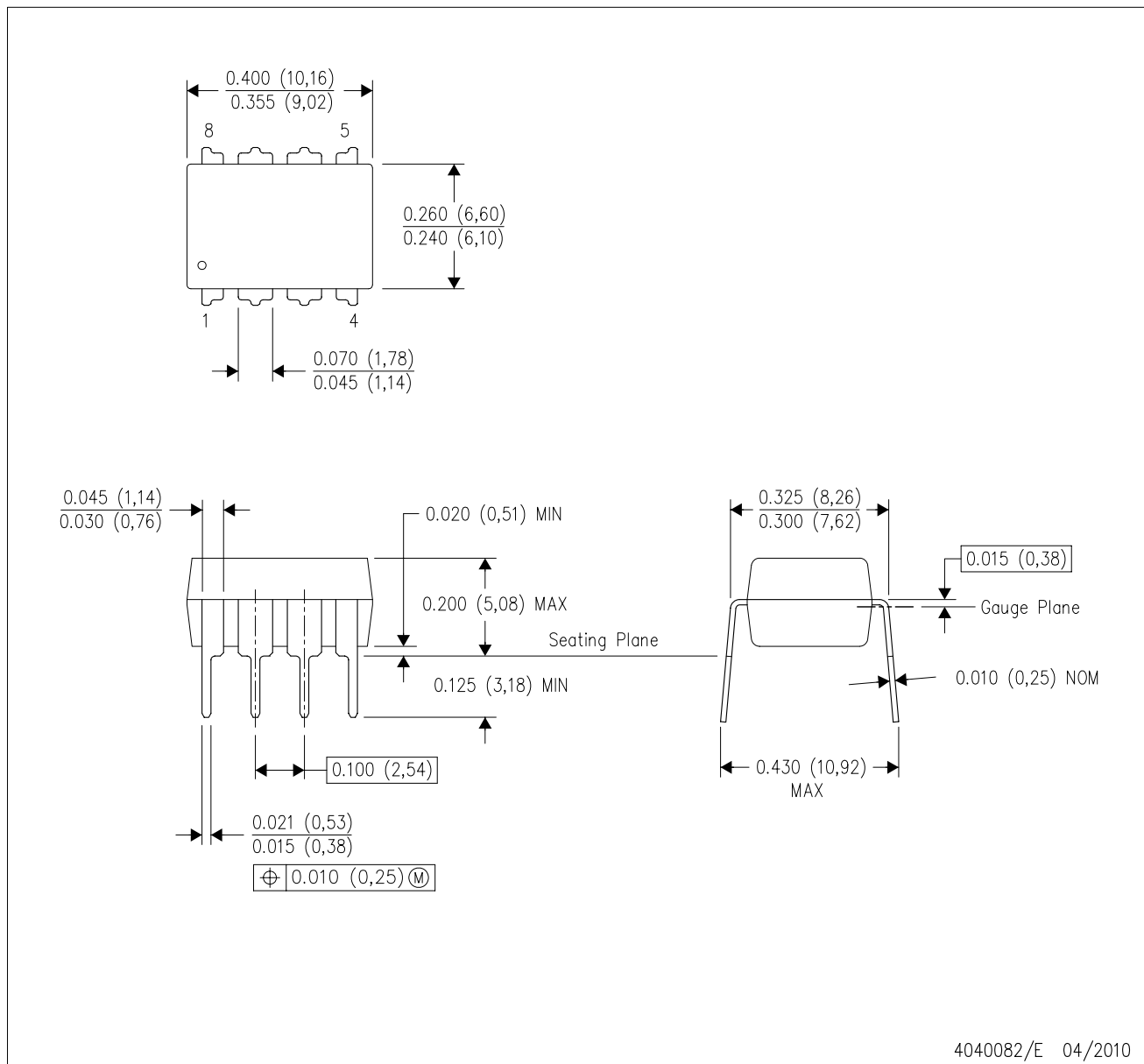
CERAMIC DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification.  
 E. Falls within MIL STD 1835 GDIP1-T8

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004



## IMPORTANT NOTICE

Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.

TI's published terms of sale for semiconductor products (<http://www.ti.com/sc/docs/stdterms.htm>) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, "Designers") understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers' applications and compliance of their applications (and of all TI products used in or for Designers' applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI's provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer's company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.